

wiring board and outer leads thereof connected to electrodes formed on the printed wiring board;
wherein each of the plurality of semiconductor packages comprises,

a die pad;

a die mounted on the die pad;

outer leads electrically connected to electrodes of the die by bonding wires, respectively;

and

the sealing member sealing therein the die, the bonding wires, parts of the outer leads and a part of the die pad, and having the upper surface on the side of the die and a lower surface on the side of the die pad;

wherein the outer leads have upper electrical connecting surfaces on the side of the upper surface of the sealing member, and lower electrical connecting surfaces on the side of the lower surface of the sealing member, respectively, and the outer leads have a height from a plane including the lower surface of the sealing member greater than that of the upper surface of the sealing member from the same plane.

REMARKS

Claims 1-13 are pending. By this Amendment, claim 9 is amended for clarification purposes only and Fig. 4 is corrected to obviate a minor drafting error. No new matter is added.

The Office Action has not acknowledged Applicants' claim of foreign priority. Accordingly, Applicants respectfully bring the Examiner's attention to the Claim of Priority and Transmittal of Certified Priority Document submitted with the filing of this application on July 27, 2001 and request appropriate acknowledgement.

The Office Action rejects claims 9-13 under 35 U.S.C. §112, second paragraph. By this